



Product Change Notification: NTD0-14TBZJ487

Date:

16-Apr-2025

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors

Notification Subject:

CCB 7041.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire as new wire material for selected ATTINY202, ATTINY212, ATTINY402, ATTINY412, MTCH1010, PIC16F1311x, PIC16F1521x and PIC16F1801x device families available in 8L SOIC (3.90mm) package at MTAI assembly site.

Affected CPNs:

[NTD0-14TBZJ487_Affected_CPN_04162025.pdf](#)

[NTD0-14TBZJ487_Affected_CPN_04162025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire as new wire material for selected ATTINY202, ATTINY212, ATTINY402, ATTINY412, MTCH1010, PIC16F1311x, PIC16F1521x and PIC16F1801x device families available in 8L SOIC (3.90mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology (HQ) (MTAI)	Microchip Technology (HQ) (MTAI)
Wire Material	Au	CuPdAu
Die Attach Material	8390A	8390A

Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	CDA194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 May 2025 (date code: 2522)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	April 2025					May 2025			
Work Week	14	15	16	17	18	19	20	21	22
Final PCN Issue Date			x						
Qual Report Availability			x						
Estimated Implementation Date									x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: April 16, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_NTDO-14TBZJ487_Qualification Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

ATTINY212-SSF

ATTINY402-SSF

ATTINY412-SSF

ATTINY212-SSFR

ATTINY402-SSFR

ATTINY412-SSFR

ATTINY212-SSNR

ATTINY402-SSNR

ATTINY412-SSNR

ATTINY212-SSN

ATTINY402-SSN

ATTINY412-SSN

PIC16F15214-I/SN

PIC16F15213T-I/SN

PIC16F15214T-I/SN

PIC16F15214T-E/SN

PIC16F15213-I/SN

MTCH1010T-V/SN

MTCH1010-V/SN

ATTINY412-SSFRA0

PIC16F15213-E/SN

PIC16F15214-E/SN

PIC16F18015-E/SN

PIC16F18015-I/SN

PIC16F18015T-I/SN

ATTINY202-SSFR

ATTINY202-SSN

Date: Tuesday, April 15, 2025

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ATTINY202-SSNR

ATTINY202-SSF

ATTINY402-SSNRA3

ATTINY202-SSNRA2

PIC16F13113T-I/SN

PIC16F13114T-I/SN

PIC16F13115T-I/SN

PIC16F13113-E/SN

PIC16F13114-E/SN

PIC16F13115-E/SN

PIC16F13113-I/SN

PIC16F13114-I/SN

PIC16F13115-I/SN

PIC16F18013-I/SN

PIC16F18014-I/SN

PIC16F18013T-I/SN

PIC16F18014T-I/SN

PIC16F18013-E/SN

PIC16F18014-E/SN

ATTINY412-SSFRA4